Explorer in Surface Engineering

Financial Results Briefing Material

for the First Half of the Fiscal Year Ending March 2022

JCU CORPORATION

TSE First Section (Stock Code: 4975)



November 4, 2021

Summary of Consolidated Financial Results for 1H FY3/22

Overview of Financial Results

For electronic components

Accounting Period of 1H FY3/22

JCU (non-consolidated): April 1 to September 30

Overseas subsidiaries: January 1 to June 30

- In China: Increase in demand for PWBs for high-performance electronic devices such as tablets and for servers Demand for chemicals increased significantly due to operations of newly acquired production lines being fully in progress
- In Taiwan: Increase in demand for semiconductor package substrates for high-performance electronic devices and servers
 - Demand for chemicals increased due to the acquisition of new production lines
- In Korea: Demand for semiconductor package substrate increased due to strong demand for semiconductors. Demand for chemicals increased due to the acquisition of new production lines

For automotive components

- In Japan: Demand for chemicals increased significantly as exports of automobiles and automotive components remained at levels higher than before the COVID-19 pandemic.
- In China: Demand for chemicals increased significantly as the recovery trend in the automotive industry continued. Although there was no impact of a decrease in automobile production due to a shortage of semiconductors, we will continue to monitor the situation closely.

Machine Business

■ Net sales decreased substantially due to the continued cautious attitude toward new investment, although there were signs of recovery in capital investment for automotive components, represented by the resumption of postponed projects.



Summary of Consolidated Financial Results for 1H FY3/22

(Millions of yen)

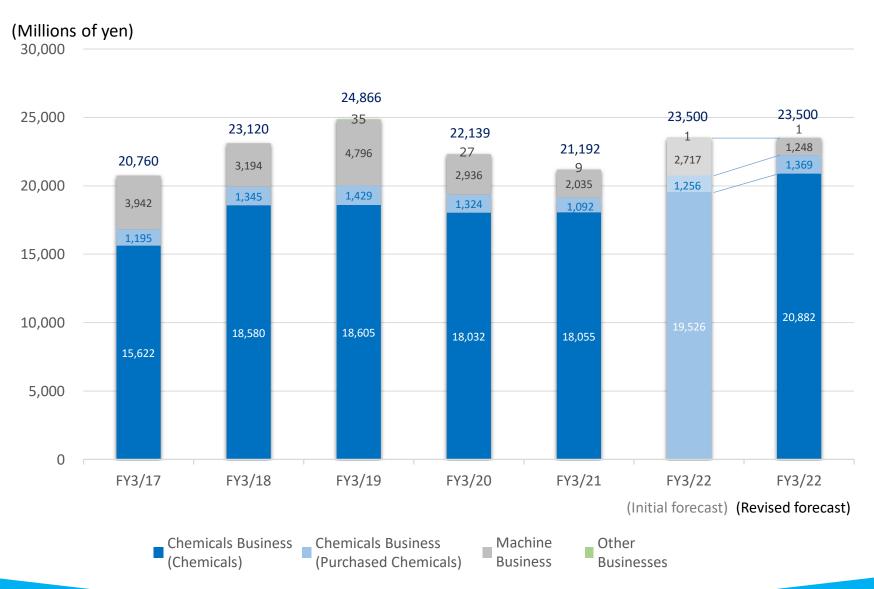
	1H FY3/20	1H FY3/21	1H FY3/22		
	Results	Results	Forecasts	Results	YoY % Change
Net sales	10,184	9,673	10,700	11,654	20.5%
Operating profit	2,919	2,917	3,250	4,350	49.1%
Ordinary profit	2,869	2,953	3,300	4,430	50.0%
Profit attributable to owners of parent	2,027	2,012	2,300	3,078	53.0%
Net income per share	74.88 yen	75.88 yen	87.60 yen	117.30 yen	-

Revised forecasts for FY3/22

(Millions of yen)

	FY3/21 Results	1H FY3/22 Results	FY3/22 Forecasts (Initial)	FY3/22 Forecasts (Revised)	Progress rate against revised forecast
Net sales	21,192	11,654	23,500	23,500	49.6%
Operating profit	6,799	4,350	7,500	8,300	52.4%
Ordinary profit	6,922	4,430	7,550	8,350	53.0%
Profit attributable to owners of parent	4,708	3,078	5,300	5,900	52.1%
Net income per share	178.33 yen	117.30 yen	201.83 yen	225.19 yen	-

Annual Sales by Business (incl. Forecast)



Foreign Exchange Rates

(Yen)

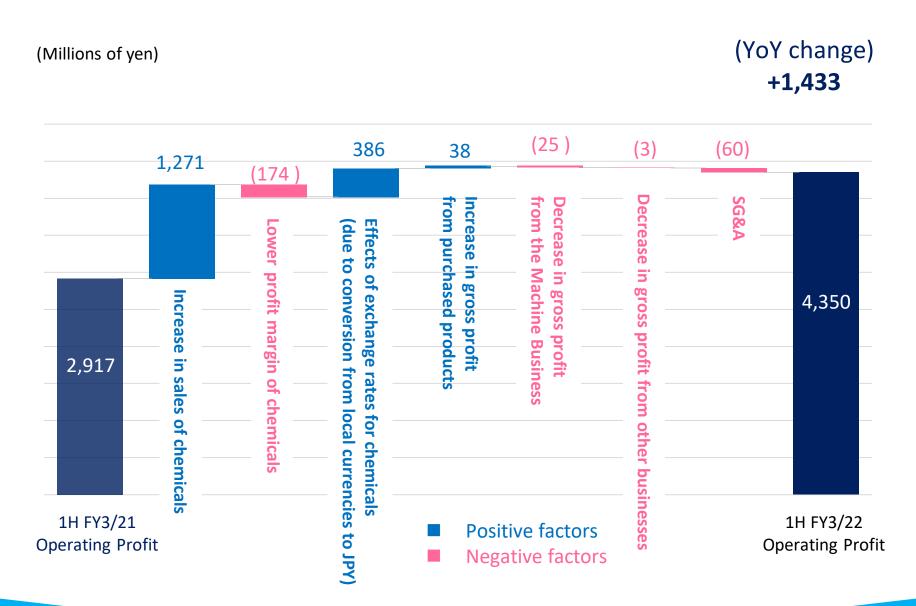
		FY3/21			FY3/22		
	1Q	2Q	3Q	4Q	(Initial forecast)	1Q	2Q
Chinese yuan (CNY)	15.61	15.39	15.38	15.48	15.50	16.36	16.66
Taiwan dollar (TWD)	3.62	3.61	3.62	3.63	3.60	3.77	3.84
Korean won (KRW)	0.0914	0.0898	0.0897	0.0906	0.0900	0.0951	0.0964

Note: The average rate for the period is used to translate Chinese yuan, Taiwan dollar and Korean won, our major foreign currencies, to Japanese yen.

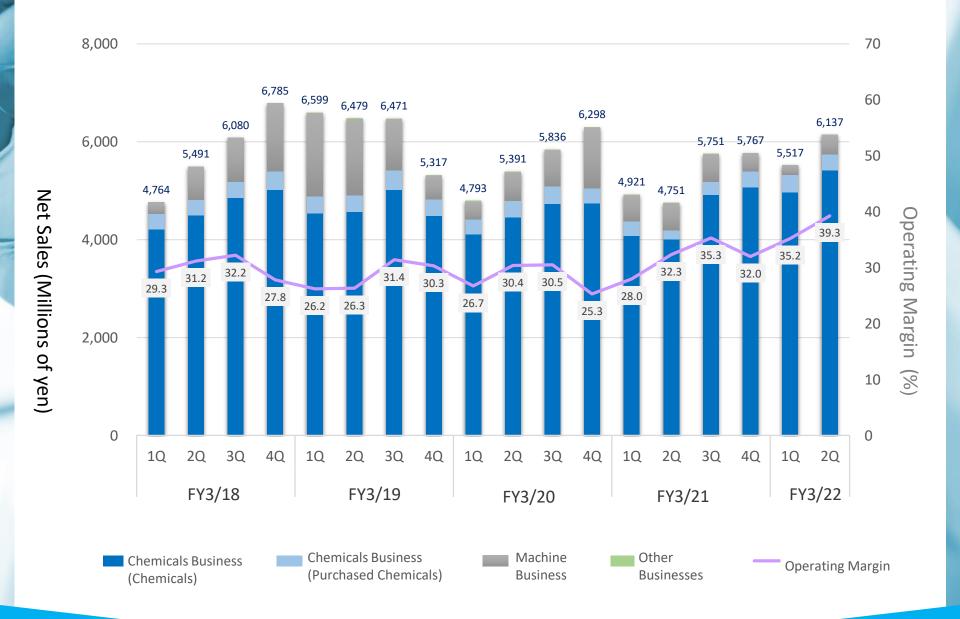
Foreign exchange sensitivity (as at the consolidated year): Changes of about 90 million yen in consolidated operating profit with 1 % change in major currency rates listed above



Changes in Consolidated Operating Profit for 1H FY3/22



Quarterly Consolidated Financial Results (By Segment)



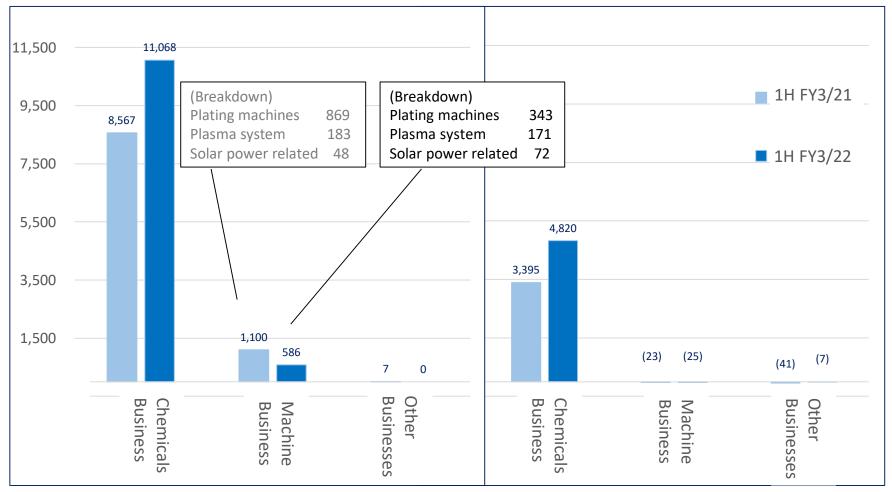


Quarterly Consolidated Financial Results



Consolidated Segment Results for 1H FY3/22

(Millions of yen)



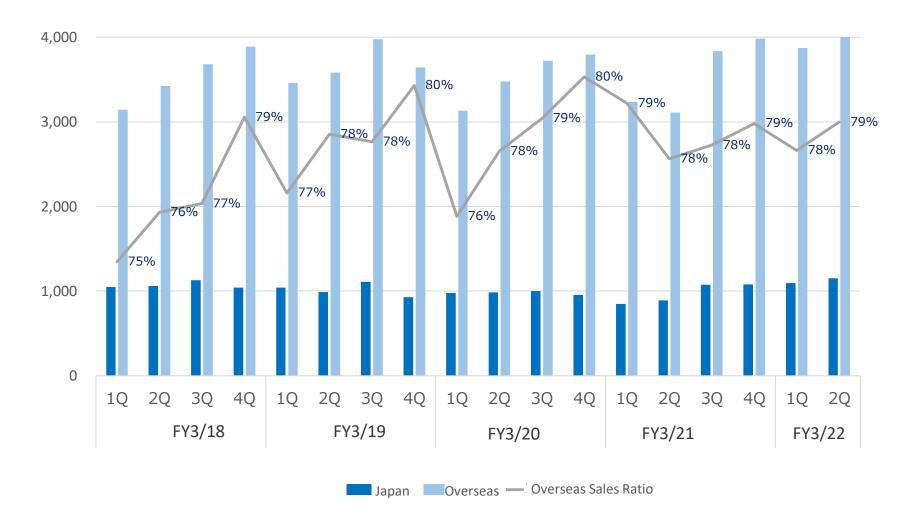
Net Sales

Segment Profit (Loss)



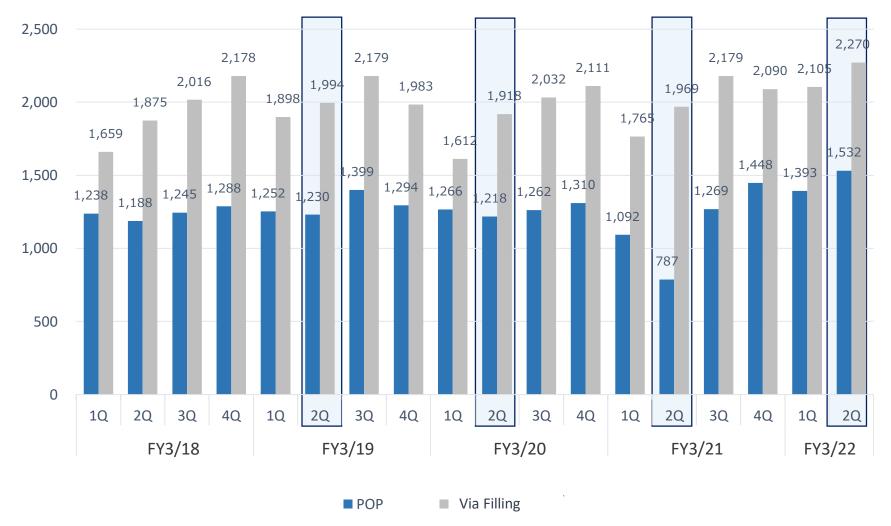
Quarterly Sales of Chemicals in Japan and Overseas

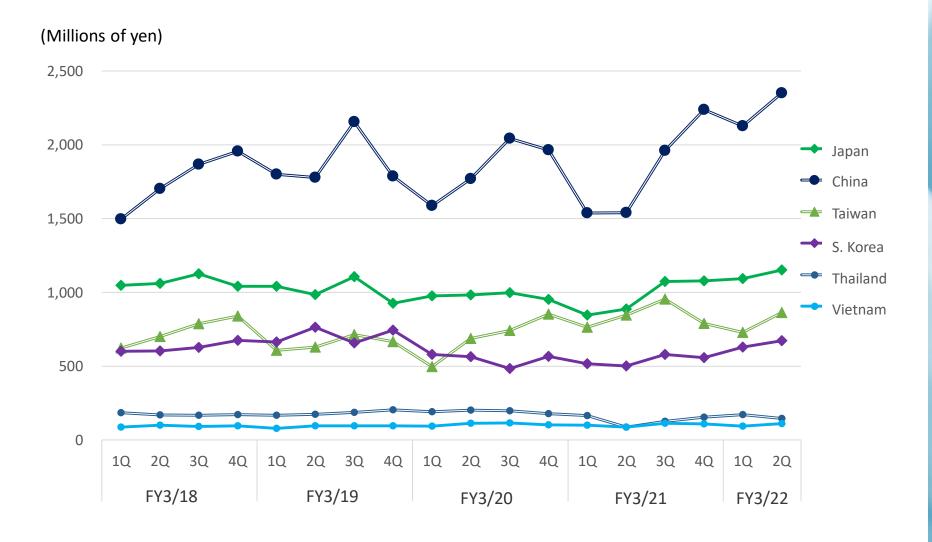
(Millions of yen)

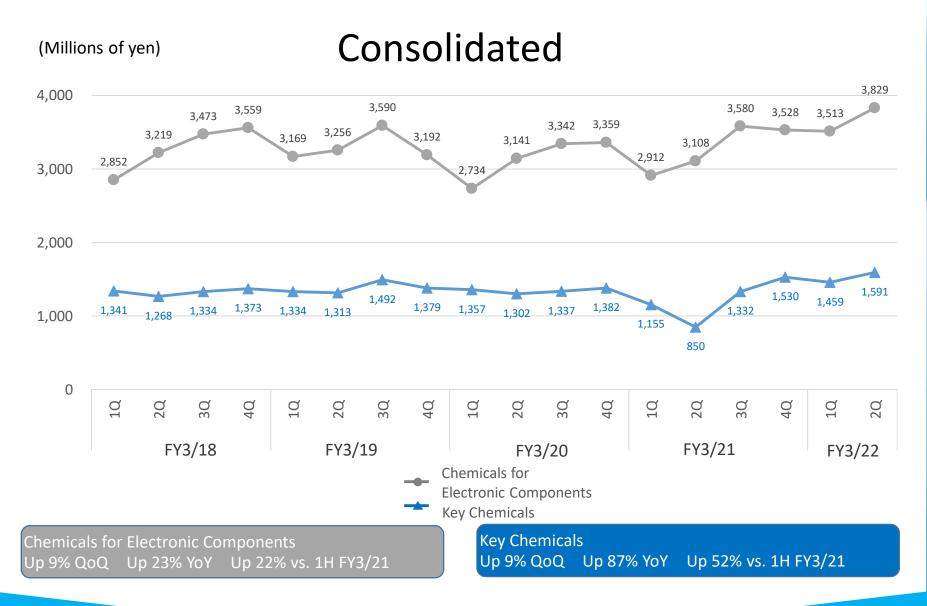


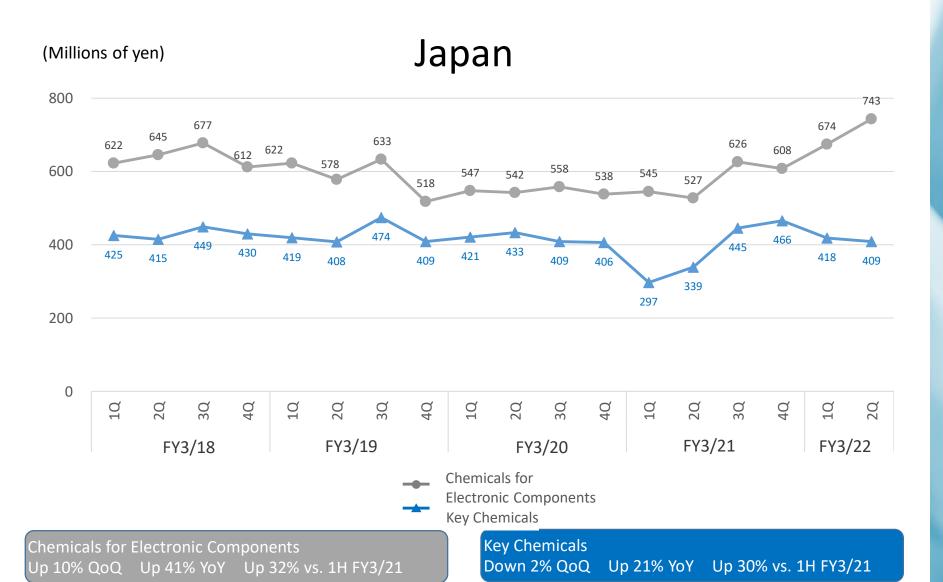
Quarterly Sales of Chemicals for POP and Via Filling

(Millions of yen)

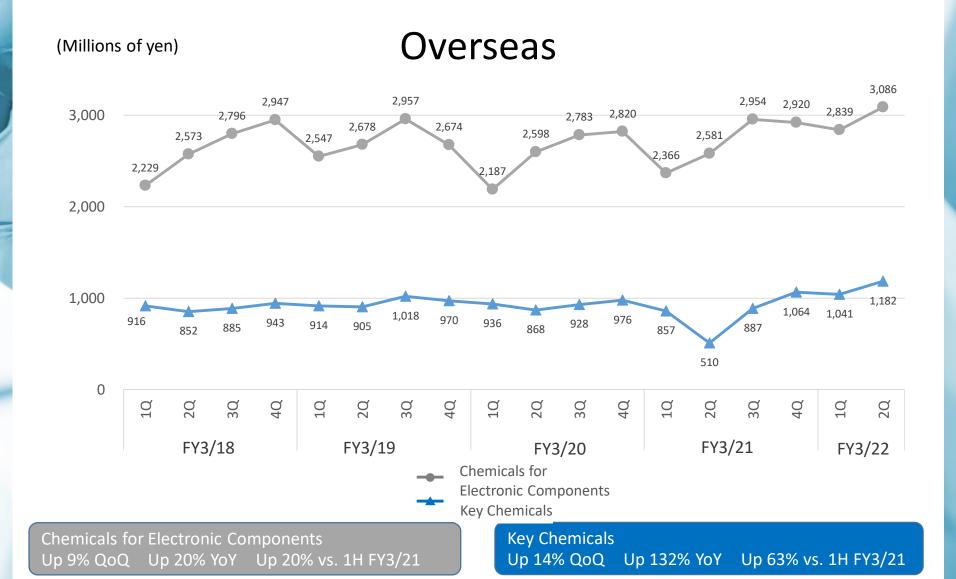


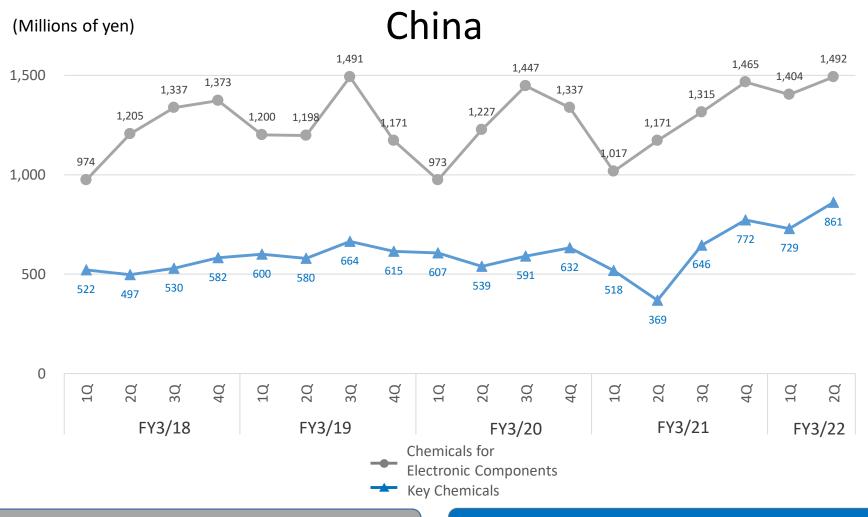








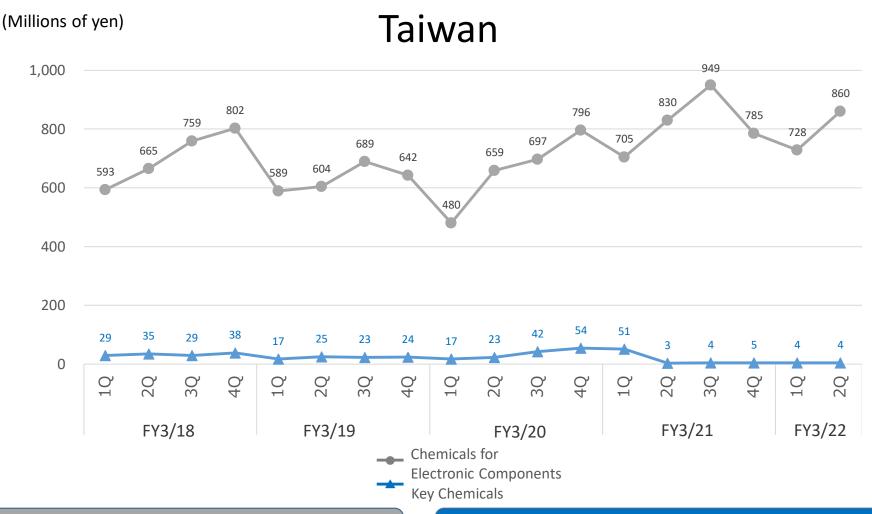




Chemicals for Electronic Components
Up 6% QoQ Up 27% YoY Up 32% vs. 1H FY3/21

Key Chemicals
Up 18% QoQ Up 133% YoY Up 79% vs. 1H FY3/21

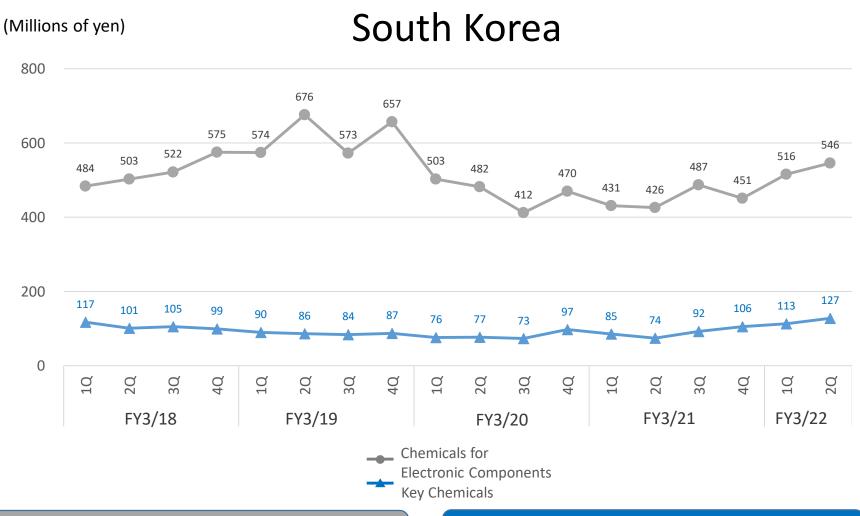




Chemicals for Electronic Components
Up 18% QoQ Up 4% YoY Up 3% vs. 1H FY3/21

Key Chemicals
Up 3% QoQ Up 33% YoY Down 85% vs. 1H FY3/21





Chemicals for Electronic Components
Up 6% QoQ Up 28% YoY Up 24% vs. 1H FY3/21

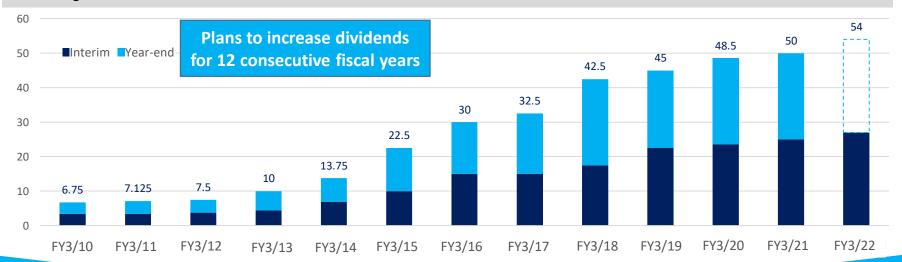
Key Chemicals
Up 12% QoQ Up 72% YoY Up 51% vs. 1H FY3/21



Dividend Forecast

		FY3/20	FY3/21	FY3/22 (Forecasts)
Divid s	Interim	23.5 yen	25.0 yen	27.0 yen
idends share	Year- end	25.0 yen	25.0 yen	27.0 yen
per	Annual	48.5 yen	50.0 yen	54.0 yen

We will continue to make investments for sustainable growth while securing liquidity on hand and maintaining stable financial base. Our basic dividend policy is to return profits to shareholders through the flexible acquisition of treasury stock, with the aim of continuing the trend of stable dividend increases.





Reference

- Company Profile
- Major Distribution Channels
- Major Products
- Usages of Chemicals and Typical Final Products

Company Profile

ISO Certificates

Founded in : December 1957

Established on : April 1, 1968

Capital stock : 1,245 million yen

Annual sales Non-consolidated: 11.6 billion yen / Consolidated: 22.0 billion yen

(For the fiscal year ended March 31, 2021)

Head office: TIXTOWER UENO 16F, 8-1 Higashiueno 4-chome, Taito-ku, Tokyo

Lines of Manufacturing and sale of surface treatment chemicals, surface

business treatment machines, and related materials

Representative : Masashi Kimura, Chairman and CEO

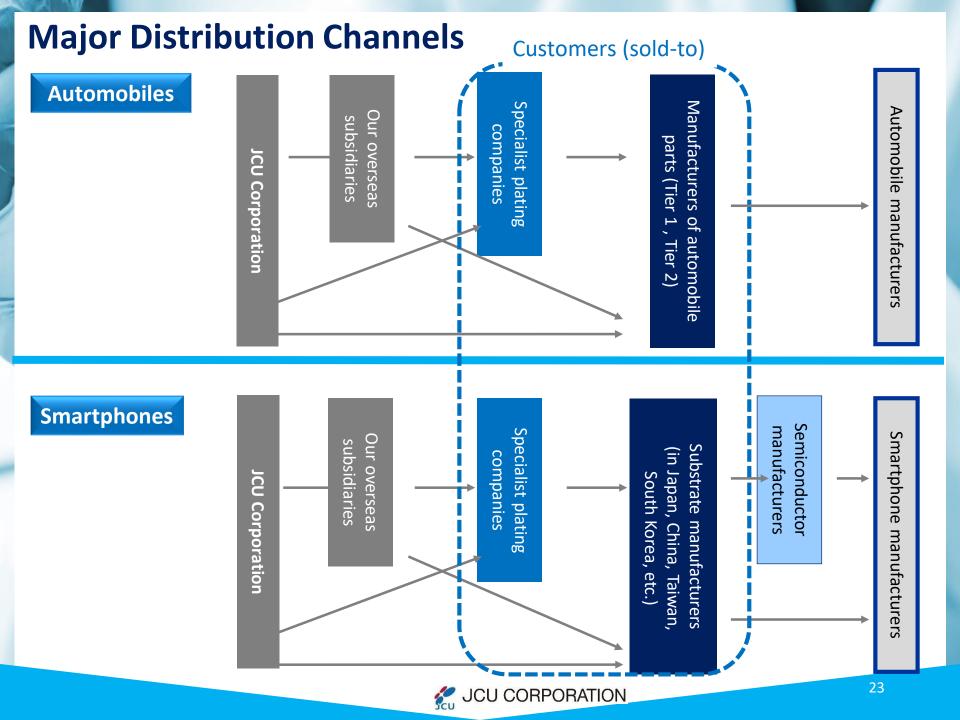
Employees : Non-consolidated: 250 / Consolidated: 561

(As of March 31, 2021)

ISO9001 Production Headquarters, Head Office Sales and Marketing Department,

and R&D Center (JCQA-0281)

ISO14001 Production Headquarters and R&D Center (JCQA-E-0143)



Major Products

Chemicals	For decoration and rust-proofing (Key chemicals)	Automotive parts (front grilles, door handles, emblems, etc.) Faucet parts (water supply equipment, showerheads, drain plugs, etc.) Construction materials (bolts, nuts, etc.)
Business	For electronic components (Chemicals for electronic components)	PWBs (reversible and multilayer substrates, build-up boards, package substrates, etc.) Electronic components (lead frames, chip components, connectors, etc.) Semiconductors (silicon wafers)

	Fully-automated surface treatment equipment	Fully-automated equipment from input of materials to completion of the plating process	
na. Ita	Peripheral equipment	Manufacturing and sale of filtration machines and other peripheral equipment to be attached to surface treatment equipment	
Machine Business	Automatic analytical control systems	Automatic management of plating solutions by analyzing concentrations chemicals and adding chemicals when an insufficient level is detected	
	Plasma system	Etching and washing devices for PWBs as part of pre-plating processes	
	Solar power generation equipment	Installation and operation of solar power generation equipment (photovoltaic panels)	

Usages of Chemicals and Typical Final Products

Des	Final products		
Key chemicals	Surface treatment (plating) chemicals for decorative and rust- proofing purposes such as those for providing a metal appearance and preventing rust.	Automotive parts, faucet parts and construction materials	
POP (Plating on Plastics) chemicals	Major products for key chemicals Chemicals for metal coating on plastics	(Automotive parts) Front grilles, emblems, etc. (Faucet parts) Showerheads, water faucet cocks, etc.	
Other key chemicals	Chemicals for metal coating on metallic materials such as copper and steel	(Construction materials) Screws, hinges, etc.	
Chemicals for electronic components	Plating chemicals for manufacturing PWBs, such as a circuit for electronic signals and an electrical contact for electronic components	5G-related components, data centers and other infrastructures and high-performance electronic devices	
Via filling chemicals (for PWBs/motherboards)	Copper plating chemicals for formulating interconnection onto PWBs/motherboards embedded in electronic products	(5G-related components) 5G base stations, in-vehicle PWBs, smart	
Via filling chemicals (for semiconductor package boards)	Copper plating chemicals for formulating interconnection onto PWBs (semiconductor packages boards) for the purpose of protecting a semiconductor chip from the external environment and mounting to PWBs	home appliances, etc. (Data centers and other infrastructures) Motherboards for communication servers et (High-performance electronic devices) Smartphones, PCs, tablets, game consoles, etc.	
Other	Plating chemicals for connecters and lead frames, etching chemicals for scraping unnecessary copper when formulating interconnection onto motherboards or semiconductor packages boards		



This material contains current plans and forecasts of future performance of JCU CORPORATION. These plans and forecast figures are prepared by the Company based on currently available information. This material does not give any assurance or guarantee of the Company's future financial performance and actual results may differ substantially from these plans for a number of conditions or developments in the future.

JCU CORPORATION's website URL: https://www.jcu-i.com/

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